SEMICONDUCTOR PACKAGE AND SEMICONDUCTOR PACKAGE FABRICATION METHOD

ABSTRACT

A semiconductor package and fabrication method are provided. The semiconductor package is highly reliable and has a construction that enables an improved fabrication yield and greatly reduces the number of steps and time required. The semiconductor package has a construction in which wiring layer 14 is supported by insulating film 13 over a range corresponding to chip electrodes 12 of semiconductor chip 11. In fabrication the semiconductor chip 11 is mounted on an interposer constituted by said wiring layer 14, insulating film 13, and adhesive layer 16 by inserting bumps 17 into holes 16 in adhesive layer 16, following which the metal junctions between wiring layer 14 and all bumps 17 as well as adhesion between semiconductor chip 11 and wiring tape 4 by means of adhesive layer 16 are realized simultaneously by using a heater plate to apply heat to adhesive layer 16 and inner lead connectors while pressing wiring tape 4 across substantially the entire range of the chip electrode formation surface.

Fig. 5